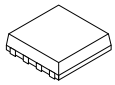
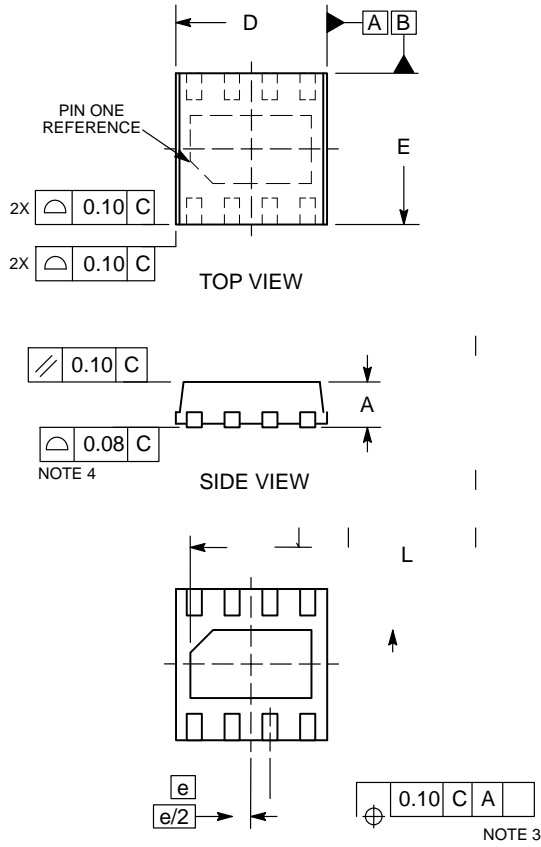


CUDFN8, 2x2, 0.5P
CASE 505AF i01
ISSUE O

DATE 20 JAN 2011



SCALE 4:1



NOTES:

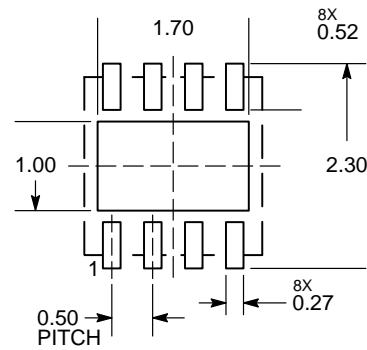
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	2.00 BSC	

D2	1.50	1.70
E	2.00 BSC	
E2	0.80	1.00
e	0.50 BSC	

L	0.25	0.35
M	---	10

RECOMMENDED



*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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